

SKM 400 GB 176 DL3



SEMITRANS™ 9

Trench IGBT Modules

SKM 400 GB 176 DL3

SKM 400 GAL 176 DL3

Preliminary Data

Features

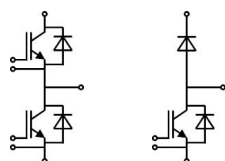
- Homogeneous Si
- Trench = Trenchgate technology
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability, self limiting to $6 \times I_C$
- Humidity according to DIN 40 040: Class F
- Climate according to DIN IEC 68 T.1: 40/125/256

Typical Applications

- AC inverter drives
- mains 575 - 750 V AC
- Public transport (auxiliary syst.)
- Wind power

Remarks

- Terminals 1,4 - 2,5 - 3,6 need to be connected externally



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Absolute Maximum Ratings		T _{case} = 25°C, unless otherwise specified		
Symbol	Conditions		Values	Units
IGBT				
V _{CES}	T _j = 25 °C		1700	V
I _C	T _j = 150 °C	T _c = 25 °C	450	A
		T _c = 80 °C	315	A
I _{CRM}	I _{CRM} =2xI _{Cnom}		600	A
V _{GES}			± 20	V
t _{psc}	V _{CC} = 600 V; V _{GE} ≤ 20 V; T _j = 125 °C V _{CES} < 1200 V		10	μs
Inverse Diode				
I _F	T _j = 150 °C	T _c = 25 °C	350	A
		T _c = 80 °C	230	A
I _{FRM}	I _{FRM} =2xI _{Fnom}		800	A
I _{FSM}	t _p = 10 ms; sin. T _j = 150 °C		1420	A
Freewheeling Diode				
I _F	T _j = 150 °C	T _c = 25 °C	470	A
		T _c = 80 °C	317	A
I _{FRM}			600	A
I _{FSM}	t _p = 10 ms; sin. T _j = 150 °C		2600	A
Module				
I _{t(RMS)}				A
T _{vj}			- 40 ... + 150 (125)	°C
T _{stg}			125	°C
V _{isol}	AC, 1 min.		9500	V

Characteristics		T _{case} = 25°C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 12 mA	5,2	5,8	6,4	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES} T _J = 25 °C T _J = 125 °C			0,0164	mA mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V T _J = 25 °C T _J = 125 °C			1200	nA nA
V _{CE0}	T _J = 25 °C T _J = 125 °C		1 0,9		V V
r _{CE}	V _{GE} = 15 V T _J = 25°C T _J = 125°C		3,3 5,2	4,2 6	mΩ mΩ
V _{CE(sat)}	I _{Cnom} = 300 A, V _{GE} = 15 V T _J = 25°C _{chiplev.} T _J = 125°C _{chiplev.}		2 2,45	2,45 2,9	V V
C _{ies}	V _{CE} = 25, V _{GE} = 0 V f = 1 MHz		26,2		nF
C _{oes}			1,1		nF
C _{res}			0,88		nF
Q _G	0V;+20V		3000		nC
R _{Gint}	T _J = 25 °C		5		Ω
t _{d(on)} t _r E _{on}	R _{Gon} = 4 Ω di/dt = 2100 A/μs	V _{CC} = 1200V I _C = 300A T _J = 125 °C	933 159 143		ns ns mJ
t _{d(off)} t _f E _{off}	R _{Goff} = 4 Ω di/dt = 2100 A/μs		1250 150 108,9		ns ns mJ
R _{th(j-c)}	per IGBT			0,09	K/W

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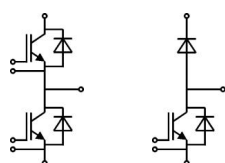
Remarks

- Terminals 1,4 - 2,5 - 3,6 need to be connected externally

Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 300 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	1,8	1,9	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	2,1	2,5	V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$	1,2	1,4	V
		$T_j = 125 \text{ }^\circ\text{C}$	0,9	1,1	V
r_F		$T_j = 25 \text{ }^\circ\text{C}$	1,7		mΩ
		$T_j = 125 \text{ }^\circ\text{C}$	3		mΩ
I_{RRM}	$I_F = 300 \text{ A}$	$T_j = 125 \text{ }^\circ\text{C}$	120		A
Q_{rr}	$di/dt = 2100 \text{ A}/\mu\text{s}$		45		μC
E_{rr}	$V_{GE} = 0 \text{ V}; V_{CC} = 1200 \text{ V}$		22		mJ
$R_{th(j-c)D}$	per diode			0,14	K/W
Freewheeling Diode					
$V_F = V_{EC}$	$I_{Fnom} = 300 \text{ A}; V_{GE} = 0 \text{ V}$	$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	1,7	1,9	V
		$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,8	2	V
V_{F0}		$T_j = 25 \text{ }^\circ\text{C}$	1,1	1,3	V
		$T_j = 125 \text{ }^\circ\text{C}$	0,9	1,1	V
r_F		$T_j = 25 \text{ }^\circ\text{C}$	2		V
		$T_j = 125 \text{ }^\circ\text{C}$	3		V
I_{RRM}	$I_F = \text{A}$	$T_j = 125 \text{ }^\circ\text{C}$			A
Q_{rr}					μC
E_{rr}	$V_{GE} = 0 \text{ V}; V_{CC} = 1200 \text{ V}$				mJ
$R_{th(j-c)FD}$	per diode			0,09	K/W
$R_{CC'+EE'}$	res., terminal-chip	$T_{case} = 25 \text{ }^\circ\text{C}$	0,35		mΩ
		$T_{case} = 125 \text{ }^\circ\text{C}$	0,5		mΩ
$R_{th(c-s)}$	per module			0,038	K/W
M_s	to heat sink M6		3	5	Nm
M_t	to terminals M6		2,5	5	Nm
w				460	g

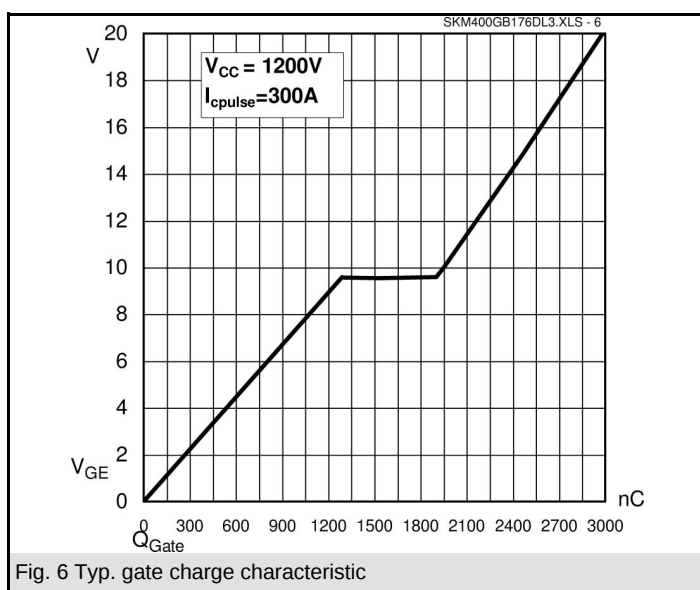
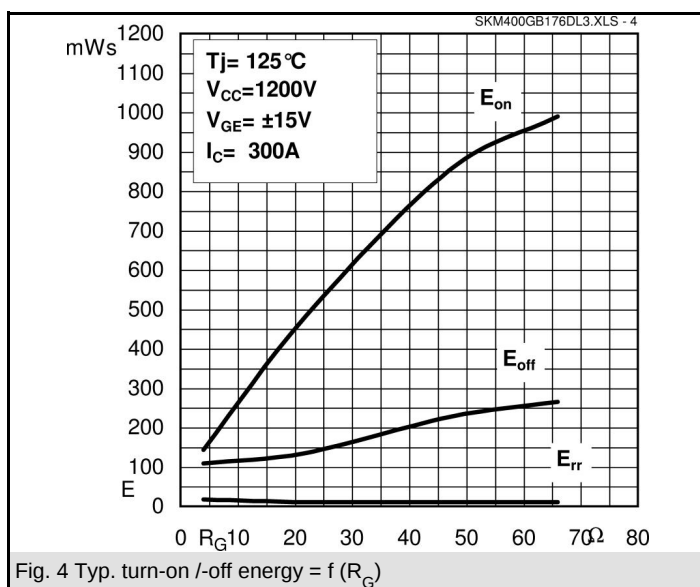
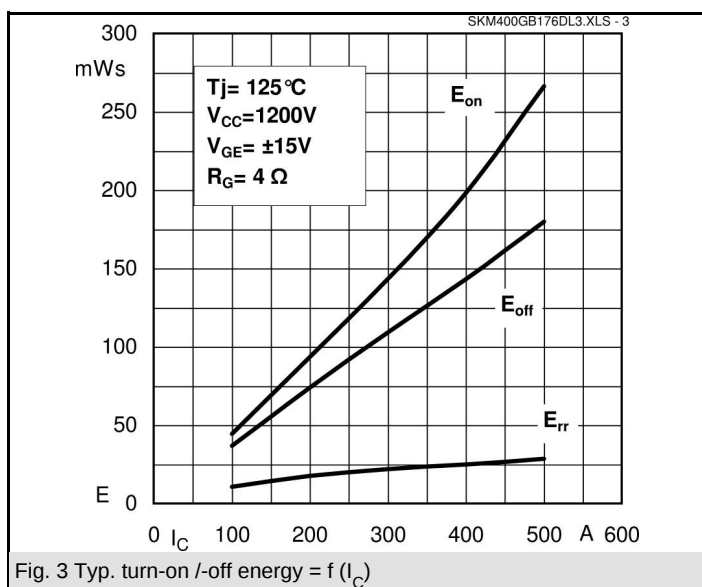
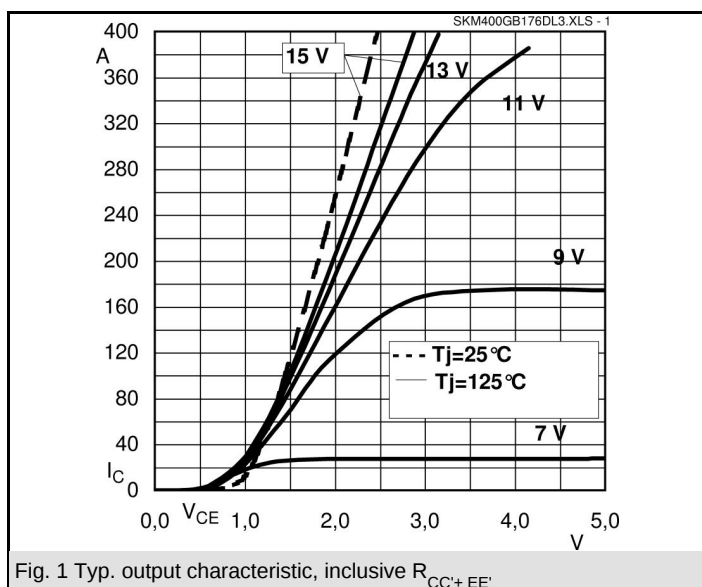
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

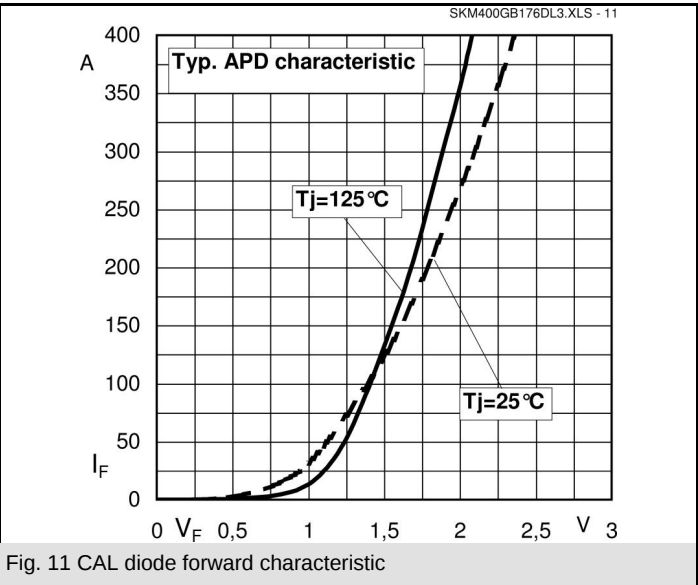
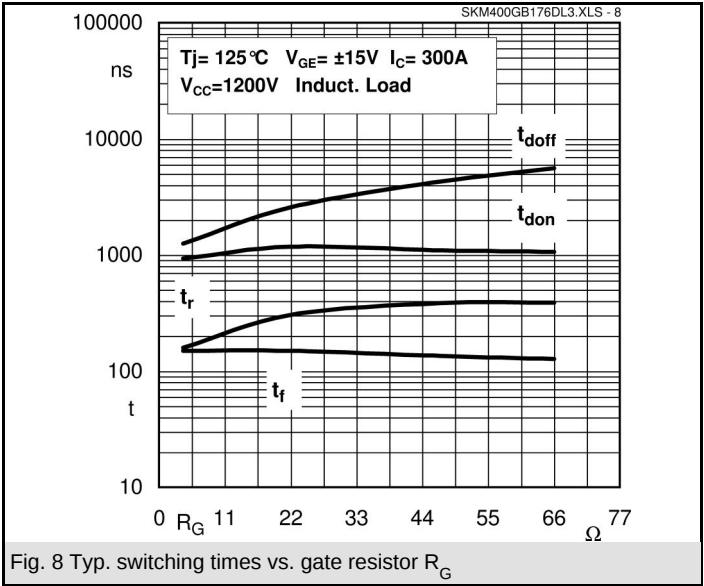
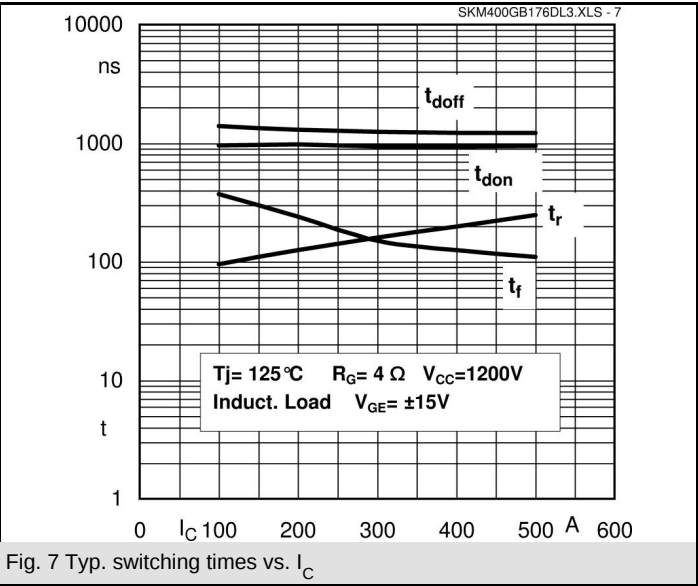
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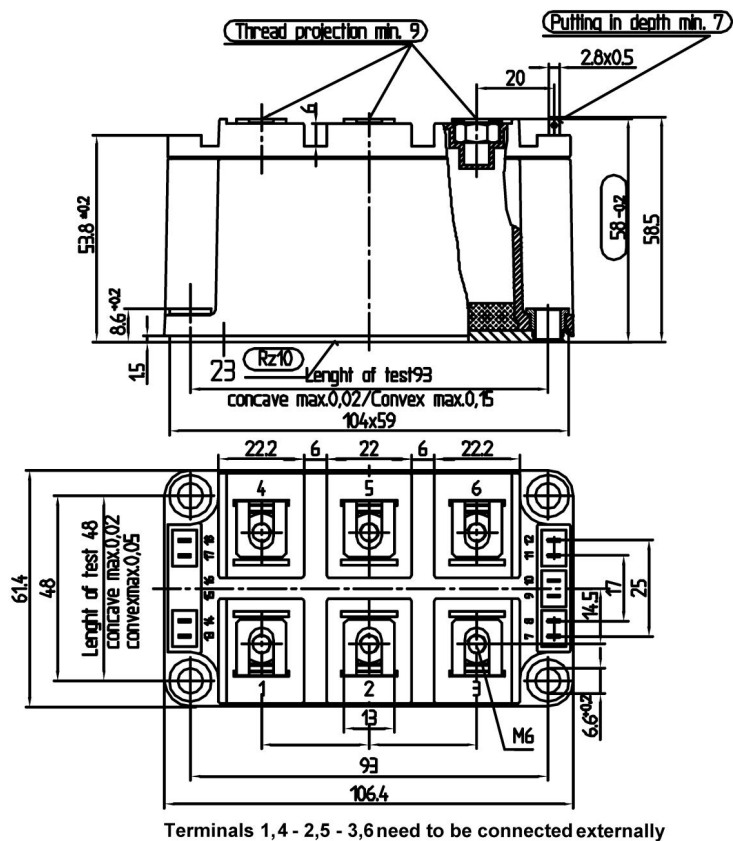


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Case D 61

